

WHAT IS CLAIMED IS:

1. An apparatus for housing electronic devices, said
5 apparatus comprising:

at least one first cutout disposed on said
apparatus, said at least one first cutout permitting air to
be convectively drawn therethrough and into said apparatus
for cooling the electronic devices housed therewithin; and

10 at least one second cutout disposed on said
apparatus, said at least one second cutout permitting the
air to ventilate outwards therefrom.

2. The apparatus of claim 1, wherein said at least
15 one second cutout is positioned above said at least one
first cutout.

3. The apparatus of claim 1, wherein said at least
one first cutout is positioned on a bottom wall of said
20 apparatus.

4. The apparatus of claim 3, further comprising at
least one base member disposed on said bottom wall of said
apparatus, wherein said at least one base member elevates

said apparatus a selected distance from a supporting base surface to permit cooler air to enter said at least one first cutout formed through said bottom wall of said apparatus.

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5. The apparatus of claim 1, wherein said at least one first cutout is positioned at a front lower portion of said apparatus, and wherein said at least one second cutout is positioned at a rear upper portion of said apparatus, to
10 maximize convective airflow over a greater area within said apparatus.

6. The apparatus of claim 1, wherein said at least one first cutout is positioned at a rear lower portion of
15 said apparatus, and wherein said at least one second cutout is positioned at a front upper portion of said apparatus, to maximize convective airflow over a greater area within said apparatus.

20 7. The apparatus of claim 1, further comprising at least one divider, wherein said at least one divider comprises at least one cutout to maximize convective airflow within said apparatus.

8. The apparatus of claim 1, further comprising at least one shelf, wherein said at least one shelf comprises at least one cutout to maximize convective airflow within
5 said apparatus.

9. The apparatus of claim 1, further comprising at least one rear aperture to accommodate the introduction of outlets, plugs and wires therethrough.

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10. The apparatus of claim 1, further comprising at least one rear aperture to accommodate the introduction of outlets, plugs and wires therethrough to permit said apparatus to sit flush against a wall surface.

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11. An apparatus for housing electronic devices, said apparatus comprising:

at least one first cutout disposed on said apparatus, said at least one first cutout permitting air to
20 be convectively drawn therethrough and into said apparatus for cooling the electronic devices housed therewithin;

at least one second cutout disposed on said apparatus, said at least one second cutout permitting the air to ventilate outwards therefrom; and

at least one shelf comprising at least one cutout
5 to maximize convective airflow within said apparatus.

12. The apparatus of claim 11, wherein said at least one second cutout is positioned above said at least one first cutout.

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13. The apparatus of claim 11, wherein said at least one first cutout is positioned on a bottom wall of said apparatus.

15 14. The apparatus of claim 13, further comprising at least one base member disposed on said bottom wall of said apparatus, wherein said at least one base member elevates said apparatus a selected distance from a supporting base surface to permit cooler air to enter said at least one
20 first cutout formed through said bottom wall of said apparatus.

15. The apparatus of claim 11, wherein said at least one first cutout is positioned at a front lower portion of said apparatus, and wherein said at least one second cutout is positioned at a rear upper portion of said apparatus, to maximize convective airflow over a greater area within said apparatus.

16. The apparatus of claim 11, wherein said at least one first cutout is positioned at a rear lower portion of said apparatus, and wherein said at least one second cutout is positioned at a front upper portion of said apparatus, to maximize convective airflow over a greater area within said apparatus.

17. The apparatus of claim 11, further comprising at least one divider, wherein said at least one divider comprises at least one cutout to maximize convective airflow within said apparatus.

18. The apparatus of claim 11, further comprising at least one rear aperture to accommodate the introduction of outlets, plugs and wires therethrough.

19. The apparatus of claim 11, further comprising at least one rear aperture to accommodate the introduction of outlets, plugs and wires therethrough to permit said apparatus to sit flush against a wall surface.

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20. A method of housing electronic devices, said method comprising the steps of:

a. placing the electronic devices within an apparatus for housing electronic devices;

10 b. convectively cooling the electronic devices therein.

21. The method of claim 20, further comprising the step of permitting cooler air to be convectively drawn into
15 said apparatus through at least one first cutout formed therethrough.

22. The method of claim 20, further comprising the step of permitting the cooler air to be convectively
20 intermixed with heat released by the electronic devices, thereby yielding a warmer air.

23. The method of claim 22, further comprising the step of permitting the warmer air to convectively ventilate out of at least one second cutout, thereby cooling the electronic devices.

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24. The method of claim 20, wherein convective cooling of the stored electronic devices is maximized by at least one divider, said at least one divider comprising at least one cutout.

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25. The method of claim 20, wherein convective cooling of the stored electronic devices is maximized by at least one shelf, said at least one shelf comprising at least one cutout.

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26. The method of claim 20, further comprising the step of passing and managing electrical conductors through at least one of said first and second cutouts.